

Technical Data Sheet

FeedBond[®] EP-2015-3-Black

Non-Conductive Adhesive

Introduction:

EP-2015-3-Black is an epoxy type adhesive designed for die-attach applications, it can be applied for BGA / lead frame package. It can be cured with minimum bleeding, and shows good adhesion on different substrates.

Characteristics:

- Excellent dispensability with minimal tailing and stringing
- Minimal bleeding and minimal volatiles

UNCURED PROPERTIES		TEST DESCRIPTION	TEST METHOD
Appearance	black	Brookfield DV-III/CP-51 @ 5rpm Brookfield DV-III/CP-51 Visc. @ 0.5rpm/Visc @ 5rpm Grind meter 25% increase in visc. @ 5rpm	FT-P006
Viscosity @ 25°C	16500 cps		FT-P008
Thixotropic Index @ 25°C	3.6		FT-P026
Grind	< 15µm		FT-P024
Work Life @ 25°C	48 hours		FT-P018
Shelf Life@ -30°C to -20°C	6 month		
CURE CONDITION		TEST DESCRIPTION	TEST METHOD
Standard Cure Condition		60 minutes @150°C	

The tables shown above are typical values only. If you need to write a specification , please request our current Standard Release Specification.

FeedBond[®] EP-2015-3-Black

Insulative Die Attach Adhesive

PHYSIOCHEMICAL PROPERTIES- POST CURE	TEST DESCRIPTION	TEST METHOD
Glass Transition Temperature 125 °C	DMA 3 Point Bending Mode	FT-M014
Coefficient of Thermal Expansion Below Tg 50 ppm/°C Above Tg 150 ppm/°C	TMA Expansion Mode	FT-M016
Dynamic Tensile Modulus @ -60°C 4500 MPa @ 25°C 3000 MPa @ 150°C 100 MPa @ 250°C 50 MPa	Dynamic Mechanical Thermal Analysis using <1.6 mm thick specimen	FT-M019
MECHANICAL PROPERTIES- POST CURE	TEST DESCRIPTION	TEST METHOD
Die Shear Strength @ 25°C >12kg/die	2mm×2mm Si die on Ag/Cu LF (80mil×80 mil)	FT-M012

p.s. The tables shown above are typical values only. If you need to write a specification, please request our current Standard Release Specification.

Instruction

Thawing

Place the container to stand vertically for 30min ~90min. **DO NOT** open the container before adhesive reaches ambient temperature to prevent the moisture condensation. Any moisture that collects on the thawed container should be removed prior to use. Adhesives that appear to have separated should not be used.

Storage

Adhesive should be stored @ -20°C to -30°C. The shelf life of the material is only valid when the material has been stored at the correct storage condition.

Availability

FeedBond adhesives are packaged in syringes or pots per customer specification. For the details, please contact our Customer Service or sales department.